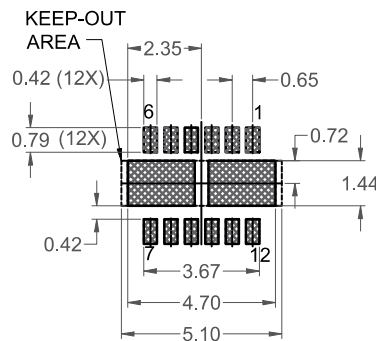
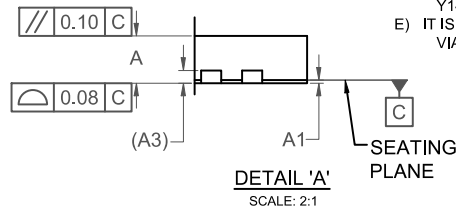
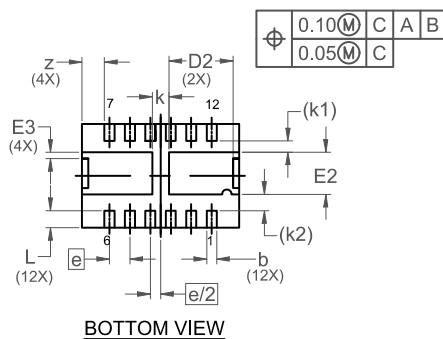
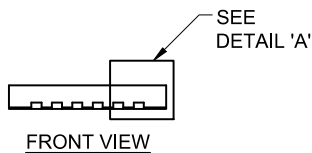
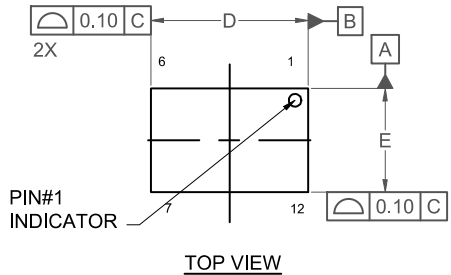

**PQFN12 3.3X5, 0.65P**  
**CASE 483BN**  
**ISSUE A**

DATE 26 AUG 2021



\*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

- NOTES: UNLESS OTHERWISE SPECIFIED  
A) THIS PACKAGE CONFORMS TO JEDEC MO-240, VARIATION BA.  
B) ALL DIMENSIONS ARE IN MILLIMETERS.  
C) DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH. MOLD FLASH OR BURRS DOES NOT EXCEED 0.10MM.  
D) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.  
E) IT IS RECOMMENDED TO HAVE NO TRACES OR VIAS WITHIN THE KEEP OUT AREA.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.70	0.75	0.80
A1	0.00	-	0.05
A3	0.20 REF		
b	0.27	0.32	0.37
D	4.90	5.00	5.10
D2	1.92	2.04	2.14
E	3.20	3.30	3.40
E2	1.24	1.34	1.44
E3	0.10	0.20	0.30
e	0.65 BSC		
e/2	0.325 BSC		
k	0.53 REF		
k1	0.36 REF		
k2	0.52 REF		
L	0.44	0.54	0.64
z	0.72 REF		

**DOCUMENT NUMBER:** 98AON13670G  
**DESCRIPTION:** PQFN12 3.3X5, 0.65P

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